



Bill of Materials

TI DESIGNS

TIDM-NFC-I2C-MODULE

Reference	Qty	Value	Part Description	Manufacturer Part Number	PCB Footprint
C1	1	10uF	CAP CER 10UF 6.3V 20% X5R 0603	GRM188R60J106ME47	0603
C2	1	220nF	CAP CER 220NF 10V 10% X7R 0402	CC0402KRX7R6BB104	0402
C3, C4, C24, C25, C26	5	27pF	CAP CER 27PF 16V 10% CH 0402	C0402CH1C270K020BC	0402
C5, C7, C9, C11, C34	4	2.2uF	CAP CER 2.2UF 10V 10% X5R 0402	C1005X5R1C225K050BC	0402
C6, C8, C10, C12, C13, C35	6	0.1uF	CAP CER 0.1UF 10V 10% X5R 0402	LMK105BJ104KV-F	0402
C15, C16,	2	1500pF	CAP CER 1500PF 16V 10% X7R 040	CGJ2B2X7R1C152K050BA	0402
C17, C18	2	1200pF	CAP CER 1200PF 10V 10% X5R 0201	0201ZD122KAT2A	0402
C19	1	220pF	CAP CER 220PF 16V 10% X7R 0201	GRM033R71C221KA01D	0402
C20, C22	2	680pF	CAP CER 680PF 16V 10% X7R 0201	GRM033R71C681KA01D	0402
C21, C27	2	10pF	CAP CER 10PF 16V 10% NP0 0402	C0402C100K4GACTU	0402
C23	1	100pF	CAP CER 100PF 16V 10% NP0 0402	C0402C101K4GACTU	0402
L2	1	150nF	CAP CER 0.15UF 10V 10% X5R 0402	GRM155R61A154KE19D	0805
L3	1	330nF	CAP CER 0.33UF 10V 10% X5R 0402	GRM155R61A334KE15D	0805
R1, R7, R8, R12,	4	1k	RES 1.00K OHM 1/16W 1% 0402 SMD	RC0402FR-071KL	0402
R2	1	47k	RES 10K OHM 1/16W 1% 0402	RC1005F103CS	0402
R3	1	220k	RES 220K OHM 1/16W 1% 0402 SMD	RC0402FR-07220KL	0402
R4	1	10k	RES 10K OHM 1/16W 1% 0402	RC1005F103CS	0402
R5, R6	2	4.7k	RES 4.7K OHM 1/10W 1% 0402 SMD	ERJ-2RKF4701X	0402
R9, R10	2	2.2k	RES 2.20K OHM 1/16W 1% 0402 SMD	RC0402FR-072K2L	0402
R11	1	1.2k	RES 1.2K OHM 1/16W 1% 0402 SMD	MCR01MRTF1201	0402

Reference	Qty	Value	Part Description	Manufacturer Part Number	PCB Footprint
U1	1	TRF7970A	IC RFID/NFC AFE 13.56MHZ 32QFN	TRF7970ARHBR	QFN32
U2	1	MSP430G2553	IC MCU 16BIT 16KB FLASH 20TSSOP	MSP430G2553IPW20R	RHB32
U3	1	I2C Translator	IC V-LEVL XLATR I2C/SMBUS 8X2SON	PCA9306DQER	PSOP-8
UFL1	1	UFL Connector	CONN UMC JACK STR 50 OHM SMD	U.FL-R-SMT(10)	U.FL
Y1	1	Crystal	13.56 MHz, (Load Cap = 12pF)	ECS-135.600-CD-0374	SMD 5X3.2

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